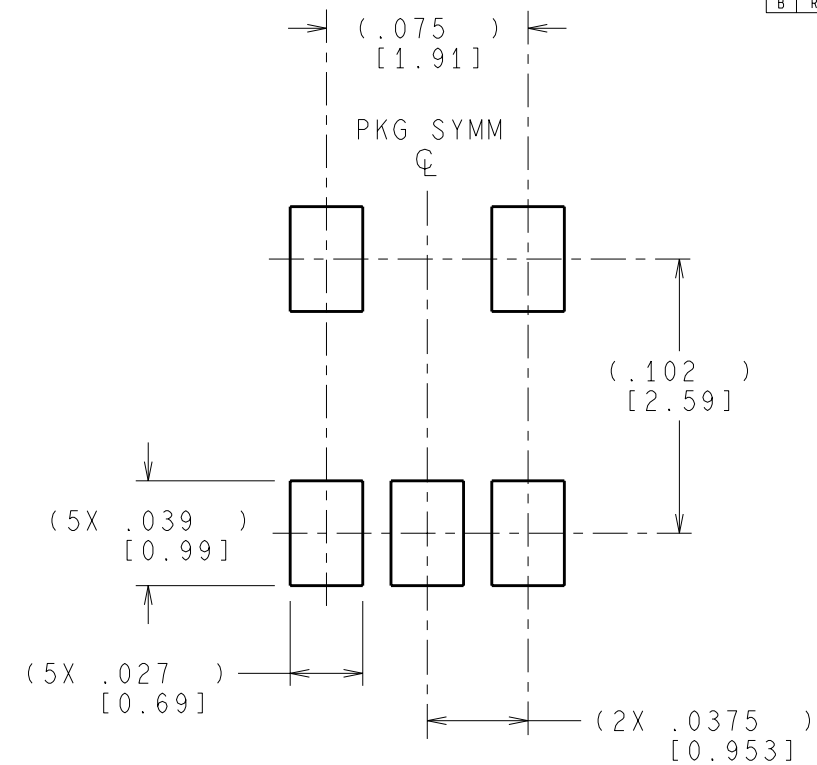
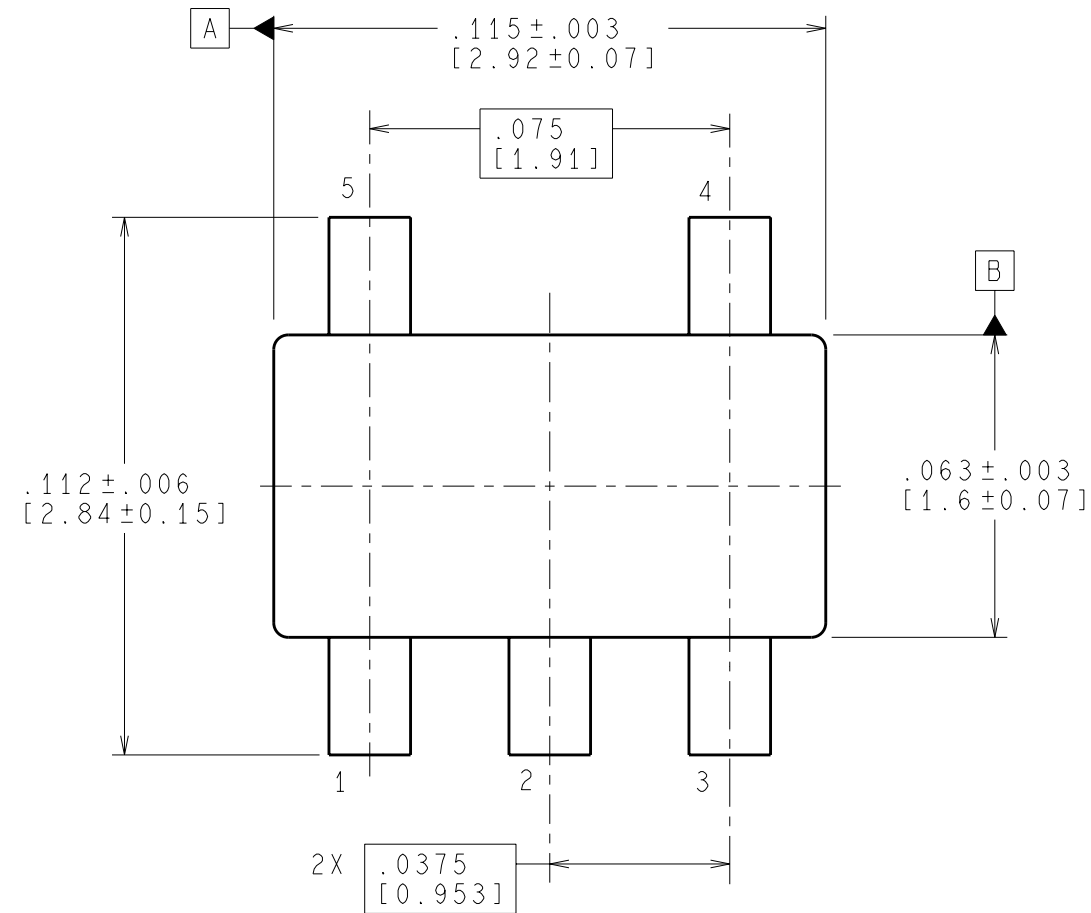
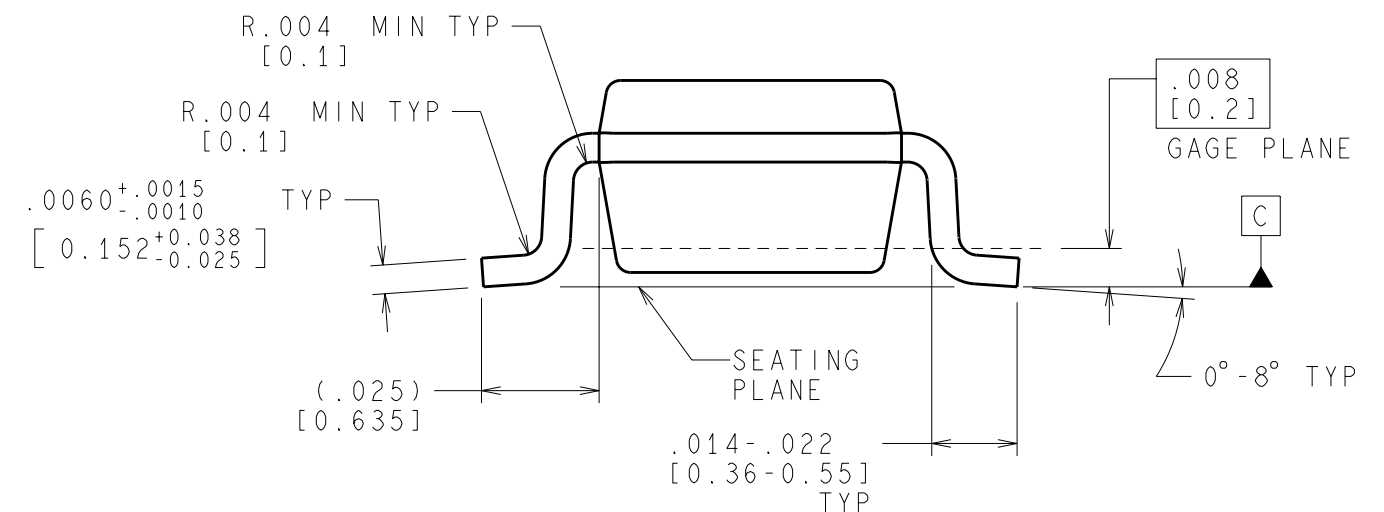
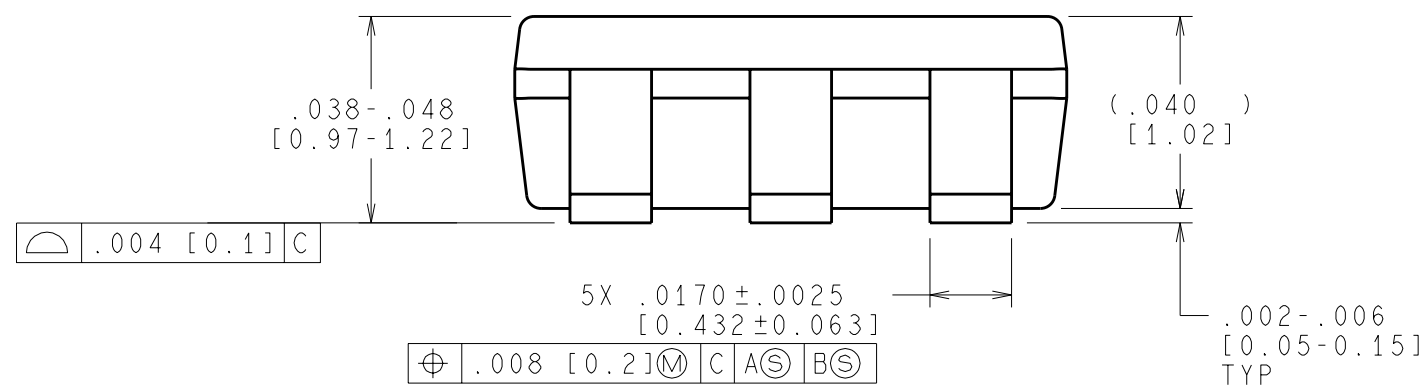


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12343	01/07/2000	TL/RW
B	REVISE NOTE 1; CHANGE DWG FORMAT TO B SIZE	983	03/27/2003	TL/RW



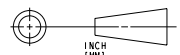
LAND PATTERN RECOMMENDATION



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-178, VARIATION AA.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	01/07/2000		
DFTG. CHK.	MARTA SUCHY	03/27/2003	MOLDED SOT-23, .115x.063x.040 in BODY, 5 LD, .0375 in PITCH	
ENGR. CHK.	RANDALL WALBERG	03/27/2003		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		NTS	B	(SC)MKT-MF05A
FORMERLY: N/A		SHEET 1 of 1		